SIM Card Interface Filter and ESD Protection

**Small Signal Discretes** 



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# BGF125 SIM Card Interface Filter and ESD Protection

## **BGF125**

Revision History: 2009-04-01, V2.0

Previous Version: 2008-05-27, V1.0

Page	Subjects (major changes since last revision)
all	target status removed
5, 6	Figure 2 and Figure 3 updated
7	Figure 5 added
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-	
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# **BGF125**

#### **Features**

- ESD protection circuit and interface filter for SIM cards
- Reduced line capacitance of 12 pF maximum
- ESD protection according to IEC61000-4-2 for ±15 kV contact discharge on external IOs
- Wafer level package with SnAgCu solder balls
- 400 μm solder ball pitch
- RoHS and WEEE compliant package



WLP-8-10-N-3D



### **Description**

BGF125 is an ESD protection and filtering circuit for SIM card interfaces. All external IOs are protected against ESD pulses of ±15 kV contact discharge according to IEC61000-4-2. The wafer level package is a green lead-free and halogen-free package with a size of only 1.15 mm x 1.15 mm and a total height of 0.6 mm

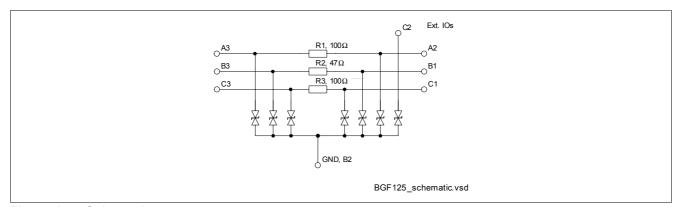


Figure 1 Schematic

Туре	Package	Marking	Chip
BGF125	WLP-8-10	25	N0745

Table 1 Maximum Ratings

Parameter	Symbol	Values			Unit	Note /
			Тур.	Max.		<b>Test Condition</b>
Voltage at all pins to GND	$V_{P}$	0	_	5	V	_
Operating temperature range	$T_{OP}$	-40	_	+85	°C	_
Storage temperature range	$T_{STG}$	-65	_	+150	°C	_
Summed up input power for all pins	$P_{in}$	_	_	60	mW	T <sub>S</sub> < 70 °C
Electrostatic Discharge According to IEC61	000-4-2					,
Contact discharge at internal pins A3, B3, C3	$V_{ESD}$	-2	_	2	kV	_
Contact discharge at external pins A2, B1, C1, C2	$V_{ESD}$	-15	_	15	kV	_

Table 2 Electrical Characteristics<sup>1)</sup>

Parameter	Symbol	Values			Unit	Note /
		Min.	Тур.	Max.		<b>Test Condition</b>
Resistors $R_1$ , $R_3$	$R_{1,3}$	80	100	120	Ω	_
Resistor R <sub>2</sub>	$R_2$	37.6	47	56.4	Ω	_
Leakage current of ESD protection diodes	$I_{L}$	_	1	100	nA	V = 3 V
		_	2	200	nA	<i>V</i> = 5 V
Breakdown voltage of ESD diodes <sup>2)</sup>	$V_{(\mathrm{BR})}$	-	18.5 -12.5	_	V	$I_{(\mathrm{BR})}$ = 1 mA $I_{(\mathrm{BR})}$ = -1 mA
Line capacitance Capacitance of all lines to GND	$C_{T}$	8	10	12	pF	V = 0 V

<sup>1)</sup> at  $T_A = 25 \,^{\circ}\text{C}$ 

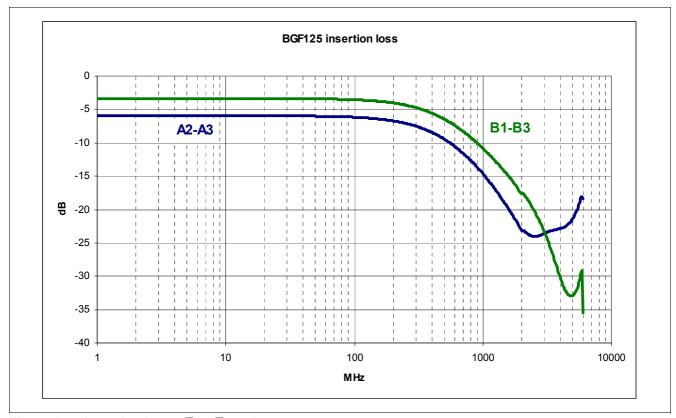


Figure 2 Insertion Loss,  $Z_S = Z_L = 50 \Omega$ 

<sup>2)</sup> after snap-back



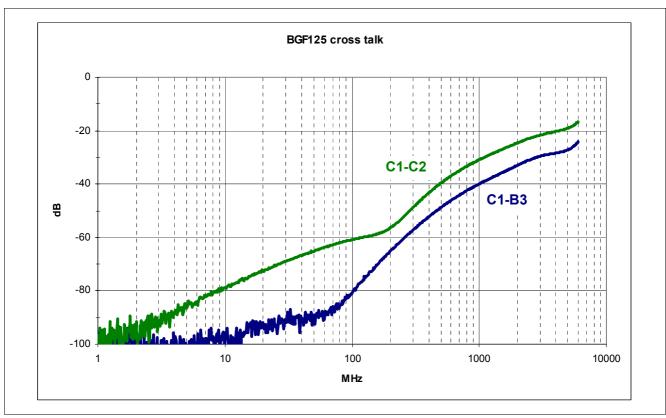


Figure 3 Typical Cross Talk,  $Z_S = Z_L = 50 \Omega$ 

## **Package Outlines**

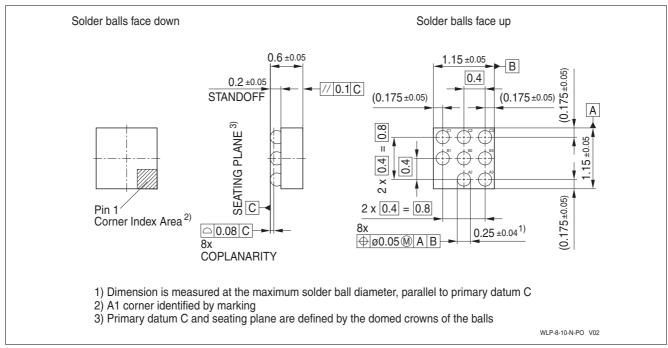


Figure 4 WLP-8-10 (Wafer Level Package)

# **Footprint**

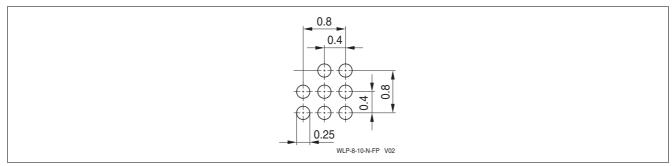


Figure 5 Recommended PCB pad design for reflow soldering

## Tape

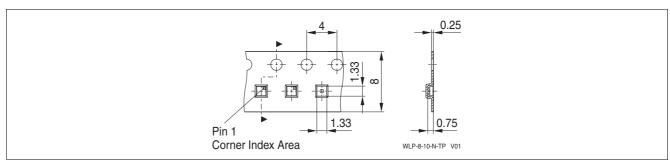


Figure 6 Tape for BGF125 / WLP-8-10

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